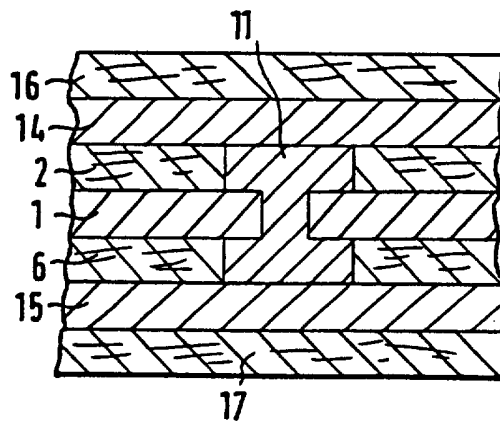




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<p>(21) International Application Number: PCT/GB89/01282 (22) International Filing Date: 27 October 1989 (27.10.89) (30) Priority data: 8825219.2 27 October 1988 (27.10.88) GB (71) Applicant (for all designated States except US): MORGAN MATERIALS TECHNOLOGY LIMITED [GB/GB]; Bewdley Road, Stourport-on-Severn, Worcestershire DY13 8QR (GB). (72) Inventors; and (75) Inventors/Applicants (for US only): GUEST, Peter, Anthony [GB/GB]; MBM Technology Limited, Victoria Road, Portslade, East Sussex BN4 1YH (GB). BETTERIDGE, Ian, Arthur [GB/GB]; MBM Technology Limited, Victoria Road, Portslade, East Sussex BN4 1YH (GB).</p>	<p>(74) Agent: PHILLIPS & LEIGH; 7 Staple Inn, Holborn, London WC1V 7QF (GB). (81) Designated States: AT, AT (European patent), AU, BB, BE (European patent), BF (OAPI patent), BG, BJ (OAPI patent), BR, CF (OAPI patent), CG (OAPI patent), CH, CH (European patent), CM (OAPI patent), DE, DE (European patent), DK, FI, FR (European patent), GA (OAPI patent), GB, GB (European patent), HU, IT (European patent), JP, KP, KR, LK, LU, LU (European patent), MC, MG, ML (OAPI patent), MR (OAPI patent), MW, NL, NL (European patent), NO, RO, SD, SE, SE (European patent), SN (OAPI patent), SU, TD (OAPI patent), TG (OAPI patent), US. Published With international search report.</p>	

(54) Title: FINE FEATURED ELECTRICAL CIRCUITS



(57) Abstract

A method of forming electrical circuits is described by the process of electroless deposition of conductive material onto a substrate having receptive and non-receptive areas such that the conductive material is deposited on the receptive areas and not on the non-receptive areas thereby forming a desired conductor pattern, comprising sequentially the steps of: i) taking a substrate comprising a receptive body (1) formed of insulating material receptive to, or treatable so as to be receptive to, electroless deposition of conductive material; and a non-receptive covering (2, 6) of insulating material overlying the receptive body; ii) removing material by stepwise machining through the depth of the non-receptive covering by ultra-violet induced ablation so as to expose the receptive body in the form of a desired conductor pattern; and iii) electrolessly depositing conductive material (11) on the exposed receptive body to form the conductor pattern. Further layers of receptive material (14, 15) and non-receptive material (16, 17) may be applied to allow further circuit layers to be made. An excimer laser is a suitable source of ultraviolet radiation.

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